

10/706624

Classification: 219/121.430

Status: 30 - DOCKETED NEW CASE - READY FOR EXAMINATION

Title: METHOD FOR SEMICONDUCTOR WAFER ETCHING


Examiner: PASCHALL, MARK

Inventor: SHIMIZU, AKIRA, et al

GAU: 3742

Bib Data report

Application Title: METHOD FOR SEMICONDUCTOR WAFER ETCHING

Application Num:  (in phx) 10706624 **Filing Date:** 11/12/2003

Effective Filing: 11/12/2003

(Location History) (Foreign/Continuity Data)

Status: 30/DOCKETED NEW CASE - READY FOR EXAMINATION **Status Date:** 08/03/2004

Patent Number: Not Issued **Issue Date:** N/A **Date of Abandonment:** N/A
Confirmation Number: 7986 **PALM Location:**

Examiner: 61092 PASCHALL, MARK Assignment Data **Group Art Unit:** 3742 **Class/Subclass:** 219/121.430

State or Country: JAPAN **Sheets/Drawing:** 1 **Total Claims:** 17
Independent Claims: 3

▼ **Inventors:**

Last name, First name:	City:	Country or State:
SHIMIZU, AKIRA	TOKYO	JAPAN
NANBA, KUNITOSHI	TOKYO	JAPAN

Attorneys: ALL **Attorney Docket No:** ASMJP.104DV1

Interference No: **Lost Case:** No **Unmatched Petition:** No **L&R Code:** 1



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BIBDATASHEET**CONFIRMATION NO. 7986**

Bib Data Sheet

SERIAL NUMBER 10/706,624	FILING DATE 11/12/2003 RULE	CLASS 219	GROUP ART UNIT 3742	ATTORNEY DOCKET NO. ASMJP.104DV1
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APPLICANTS

Akira Shimizu, Tokyo, JAPAN;

Kunitoshi Nanba, Tokyo, JAPAN;

** CONTINUING DATA *****

This application is a DIV of 10/068,092 02/05/2002 PAT 6,764,572

** FOREIGN APPLICATIONS *****

JAPAN 2001-056685 03/01/2001

IF REQUIRED, FOREIGN FILING LICENSE GRANTED

** 02/20/2004

Foreign Priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no	STATE OR COUNTRY JAPAN	SHEETS DRAWING 1	TOTAL CLAIMS 17	INDEPENDENT CLAIMS 3
35 USC 119 (a-d) conditions met <input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance				
Verified and Acknowledged	Examiner's Signature	Initials		

ADDRESS

20995
 KNOBBE MARTENS OLSON & BEAR LLP
 2040 MAIN STREET
 FOURTEENTH FLOOR
 IRVINE , CA
 92614

TITLE

Method for semiconductor wafer etching

FILING FEE RECEIVED	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees
		<input type="checkbox"/> 1.16 Fees (Filing)
		<input type="checkbox"/> 1.17 Fees (Processing Ext. of time)
		<input type="checkbox"/>